Compound Semiconductor Materials Japan TC Chapter

Meeting Summary and Minutes

SEMI Standards Japan Summer Meetings 2025
Monday, June 30, 2025 14:00 – 16:30 JST
SEMI Japan Office, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

TBD in conjunction with SEMICON Japan 2025

Tokyo Big Sight, Tokyo, Japan/ OVTCCM (Hybrid)

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Masayoshi Obara (Shin-Etsu Handotai)
SEMI Staff: Akiko Yoshida (SEMI Japan)

Company	*Last*	*First*	*Company*	*Last*	*First*
AIST	*Senzaki*	*Junji*	*Self*	*Yamamoto*	*Toshiaki*
Kohzu Precision	Kuwabara	Satoshi	*Self*	*Yoshise*	*Masanori*
Kushan Kinglai Hygienic Materials	*Kingson*	*Austin*	SOL	Takano	Tomonobu
Mitsubishi Electric	Iwamatsu	Toshiaki	Shin-Etsu Handotai	Obara	Masayoshi
Nidek	*Kondo*	*Toshiyuki*	*SiC Alliance*	*Toda*	*Kenji*
Resonac	*Matsuse*	*Akihiro*	SEMI Japan	Koga	Nahoko
Self	Kitabatake	Makoto	SEMI Japan	Yoshida	Akiko

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7211A	Line Item Revision to SEMI M92-0824, Specification for 4H-SiC Homoepitaxial Wafer	
Line Item 1	Revise the test pattern in section 6.4.3.1	**Passed** with editorial changes
Line Item 2	Revise the specification of test points coordinates in section 6.4.3.2 (including subsequent table number changes)	**Passed** as balloted

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

#1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

#2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
None			

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
CSM_20250630-01	SEMI Staff	To forward ballot review results of Doc.#7211A to the ISC A&R SC for procedural review.
CSM_20250630-02	TC members	To discuss the remaining issues of SiC Epitaxial Wafer.

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
20220119-03	Silicon Carbide Substrate Liaison TF leaders and SiC Epitaxial Wafer liaison TF leaders	To confirm the contents of Document #6693, 6767-9 and their ballot schedule and share them to the JA TF members and hold meetings as necessary. →Closed
CSM_20240521-01	SEMI Staff	To send Doc.#7211 Line Item 3-5 adjudication results to the ISC A&R SC for procedural review. →Closed
CSM_20240521-02	SEMI Staff	To have an explanatory session for Connect@SEMI. →Closed

1 Welcome, Reminders, and Introductions

Masayoshi Obara (Shin-Etsu Handotai) called the meeting to order at 14:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01_Meeting Reminders

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written.
By / 2nd:	Masanori Yoshise (Self)/ Makoto Kitabatake (Self)
Discussion:	None.
Vote:	11-Y 0-N. Motion passed.

Attachment: 02_CSM JA TC Minutes_20241212_v1.0

3 Liaison Reports

3.1 *Japan Regional Standards Committee (JRSC)*

Akiko Yoshida (SEMI Japan) reported for the JRSC that the meeting was held on Thursday, April 17. Topics included:

- Daisuke Sado (Eagle industry) was appointed by the ISC to be a co-chair of JRSC. With this, Tadahiro Furukawa (Yamagata University) stepped down from co-chair position.
- The Planning Meeting will be held on Thursday, August 28, inviting all the TF leaders as well as TC co-chairs to deepen knowledge or insights regarding standardization. The theme this year would be “Transparency in the Supply Chain and SEMI Standards.” More details will be announced as soon as they are finalized.

3.2 *Global Coordinating Subcommittee (GCS)*

Akiko Yoshida (SEMI Japan) reported for the GCS that there was no GCS discussion or voting between Compound Materials Japan TC Chapter meetings.

3.3 *Compound Semiconductor Materials Europe TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the Compound Semiconductor Materials Europe TC Chapter according to the recently published meeting minutes. Of note:

- Last meeting was held on April 1, 2025 online and next meeting will be held during SEMICON Europa (exact date is TBD).
- Doc.#7280, Line-Item Revision to SEMI M83-0820, Test Method For Determination Of Dislocation Etch Pit Density In Monocrystals Of Iii-V Compound Semiconductors (Line Item 1, 2, and 3) passed as balloted.
- Doc.#R7225 was approved and is pending publication.

Attachment: 03_CSM EU TC Minutes 04012025

3.4 *Compound Semiconductor Materials North America TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the Compound Semiconductor Materials North America TC Chapter that there had been no updates from the previous meeting back in 2022.

3.5 *Compound Semiconductor Materials China TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the Compound Semiconductor Materials China TC Chapter. Of note:

- Last meeting was held on June 17, 2025 online and next meeting is TBD.
- Doc.#6769C, New Standard: Test Method for Residual Stress of Silicon Carbide Wafers by Photoelastic Effect failed the TC Chapter review and was returned to the TF for rework. The TF will discuss whether they will abolish the SNARF or not.
- SiC Epitaxial Wafer TF plans to draft a new standard about 4H-SiC epitaxial wafer carrier concentration test and thickness test. The TF is currently working with various epitaxial companies, substrates, device companies and equipment manufacturers in the investigation of the test method.
- Silicon Carbide Substrate TF is drafting Doc.#6767, New Standard: Test Method for Flatness of Silicon Carbide Wafers by Optical Interference.

Attachment: 04_CSM China TC Chapter June 2025

4 SEMI Staff Report

Akiko Yoshida (SEMI Japan) gave the SEMI Staff Report. Of note:

- The second Global Standards Summit (GSS) will be held at SEMICON West 2025 in Phoenix, Arizona to identify standards-critical areas and work towards an industry standardization strategy for the next 3- and 7-year time horizons. In GSS 2025, continued discussion on standards critical topics covered in GSS 2024 is expected in addition to additional new topics.
- SEMI Standards Style Manual Rev. 10 is being reviewed by the ISC Regulations SC. It will be published soon.
- SEMI University Japan Store launched in June, 2024, which provides SEMI Japan original e-learning courses with Japanese audio or subtitles including SEMI Standards tutorials.

Attachment: 05_Staff Report June 2025 v5

5 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

5.1 *Doc.#7211A, Line Item Revision to SEMI M92-0824, Specification for 4H-SiC Homoepitaxial Wafer*

5.1.1 Line Item 1: Revise the test pattern in section 6.4.3.1

Passed with editorial changes.

5.1.2 Line Item 2: Revise the specification of test points coordinates in section 6.4.3.2 (including subsequent table number changes)

Passed as balloted.

Attachment:	06_4-25-Compound Semiconductor Materials_Tally_20250530
	07_7211A_ProceduralReview

6 Subcommittee and Task Force Reports

6.1 *Silicon Carbide Substrate Liaison Task Force*

Masayoshi Obara (Shin-Etsu Handotai) reported for the Silicon Carbide Substrate TF that there had been no activities.

6.2 *SiC Epitaxial Wafer Liaison Task Force*

Masayoshi Obara (Shin-Etsu Handotai) reported for the SiC Epitaxial Wafer Liaison TF that the TF met on June 10 and discussed the voting results of Doc.#7211A which was submitted for Cycle 4, 2025. Please refer to 5.1 for more details.

7 Old Business

7.1 *Project Period Review*

No SNARF will be expiring soon.

7.2 *5-Year Review*

No document is subject for 5-year review within this year.

8 New Business

At the next TC Chapter meeting, the remaining issues regarding SiC Epitaxial Wafer will be discussed.

9 Next Meeting and Adjournment

The next meeting is scheduled during SEMICON Japan 2025 at Tokyo Big Sight, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid). Exact date is TBD. Refer to http://www.semi.org/standards-events for the current list of events.

Adjournment: 16:30.

Respectfully submitted by:

Akiko Yoshida
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SEMI Japan
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Email: ayoshida@semi.org

Minutes tentatively approved by:

Masayoshi Obara (Shin-Etsu Handotai), Co-chair	July 2, 2025

Table 14 Index of Available Attachments[#1]

Title	*Title*
01_Meeting Reminders	05_Staff Report June 2025 v5
02_CSM JA TC Minutes_20241212_v1.0	06_4-25-Compound Semiconductor Materials_Tally_20250530
03_CSM EU TC Minutes 04012025	07_7211A_ProceduralReview
04_CSM China TC Chapter June 2025	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Akiko Yoshida at the contact information above.